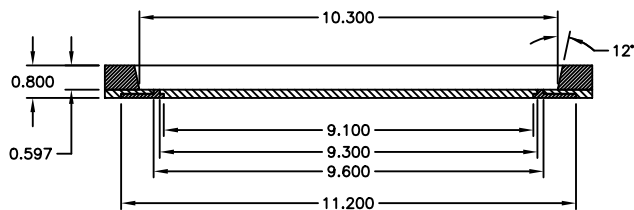
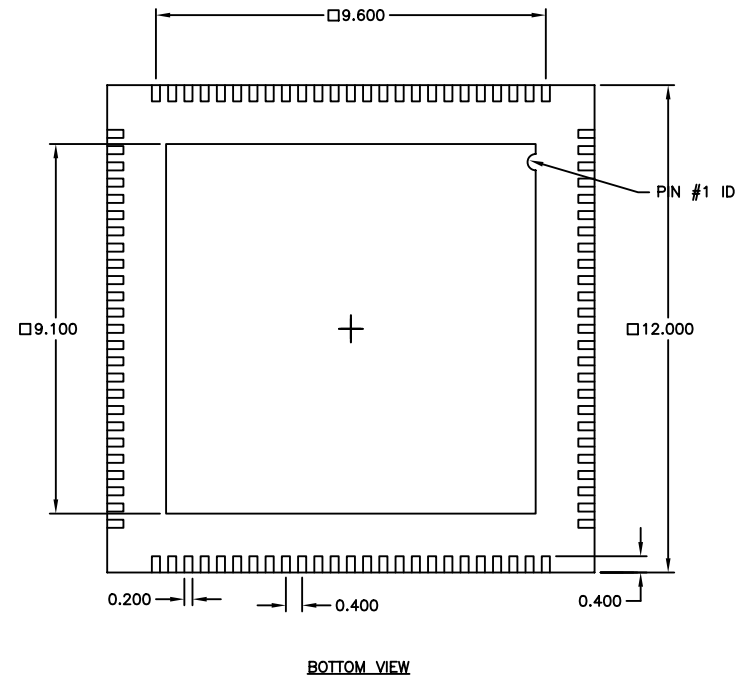
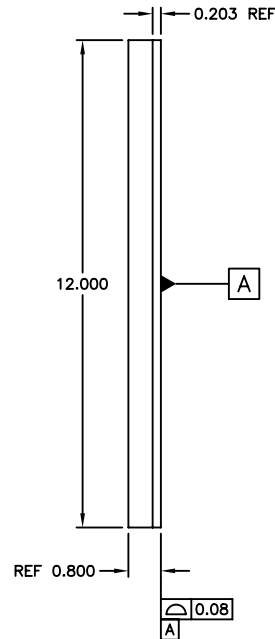
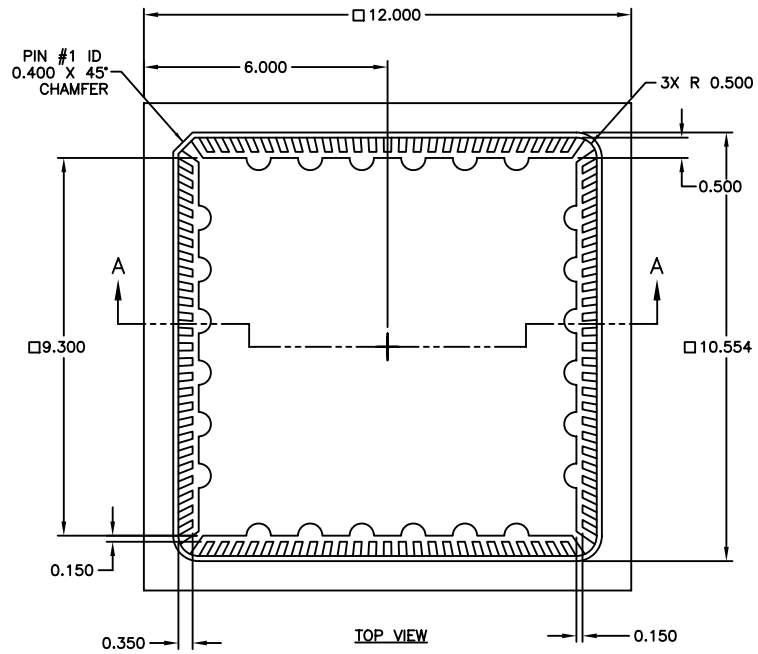


REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
	3/3/11	PRE-PRODUCTION RELEASE	S. SWEN



SECTION A-A

NOTES

- MATERIALS:  
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008  
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.
- FINISH:  
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-28074, CLASS 1, 100 TO 300 MICROINCHES (2.5um - 7.6um) THICK.  
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um - 2um) THICK).  
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra).
- PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
- PACKAGE CONFORMS TO JEDEC MO-220.

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER TOLERANCES ARE:  
X.XX ± 0.15 X.XXXX ± ---  
X.XXX ± 0.050 ANGLES: ± 1°

**DO NOT SCALE DRAWING**

DRAWN BY	CAD DEPT.	DATE	5/1/10
APP BY	STEVE S.	DATE	5/1/10
CUSTOMER	---		
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12mm X 12mm  
QFN 100 LEAD 0mPP

SIZE	PART NO.	REV
A	QP-QFN100-12-.4MM	A1
SCALE	NONE	CAD FILE
		SHEET 1 OF 1